HIGH-DENSITY ARRAYS

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HIGH-DENSITY ARRAYS
EXTREME PERFORMANCE • OPEN-PIN-FIELD • LOW-PROFILE

SEAM/SEAF
Shown with 400 pins

VARIETY OF OPTIONS:
• **Pitch**: 0.635 mm, 0.80 mm, 1.27 mm
• **Pin/Pair Count**: 8 to 560; 1,000+ Roadmap
• **Stack Height**: 4 mm to 40 mm
• **Options**: Right-angle, press-fit tails, 85 Ω tuned, standoffs

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EXTREME PERFORMANCE ARRAYS

• 4.0 Tbps aggregate data rate - 9 IEEE 400G channels
• Two points of contact ensure a more reliable connection
• 112 fully shielded differential pairs per square inch
• Extremely low crosstalk (to 40 GHz) and incredibly tight impedance control
• Minimal variance in data rate as stack height increases
• Utilizes 40% less space with the same data throughput as compared to traditional arrays
• Terminal with latching available to mate with NovaRay® cable (NVAM-C)

HIGH-PERFORMANCE ARRAYS

• Flexible open-pin-field and cost optimized, extreme performance solution
• Low-profile 5 mm stack height and up to 10 mm
• 0.635 mm pitch
• Four row design with up to 400 total pins; roadmap to 1,000+ pins
• Data rate compatible with PCIe® 5.0 and 100 GbE
• Cable assembly in development

HIGH-DENSITY ARRAYS

• Up to 400 I/Os in a 4-row, open-pin-field design
• 0.635 mm pitch Edge Rate® contacts
• Low profile 5 mm stack height and slim 5 mm width
• PCIe® 5.0 capable
• Compatible with mPOWER® for a power/signal solution
• Other stack heights in development
1.27 mm PITCH ARRAYS

- Maximum grounding and routing flexibility
- Up to 560 Edge Rate® contacts optimized for signal integrity performance
- 7 mm to 40 mm stack heights; right-angle available
- Supports high-speed protocols such as Ethernet, PCI Express®, Fibre Channel and InfiniBand™
- Standards: VITA and PISMO™ 2
- Compatible with mPOWER® (UMPT/UMPS) for power/signal flexibility

**OPEN-PIN-FIELD FLEXIBILITY**

- Differential Pair
- Single-Ended
- Power

**SEAM-RA**

**SEAM/SEAF**

1.12 mm (.044")
contact wipe

Solder charge terminations (IPC-A-610F & IPC J-STD-001F Class 3)

Elevated stack heights available (SEAR)

Press-fit tails available (SEAMP/SEAFP)

Jack screw standoffs (JSO)

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HIGH-DENSITY 0.80 mm PITCH ARRAYS

- 2x the density of 1.27 mm pitch arrays
- Up to 500 Edge Rate® contacts
- 7 mm and 10 mm stack heights
- Lower insertion/withdrawal forces
- Solder charge terminations for a secure connection to board
- Compatible with mPOWER® for power/signal flexibility

LOW PROFILE ARRAYS

- Up to 400 total pins in 4, 6 or 8 rows
- 4 mm, 4.5 mm and 5 mm stack heights
- 1.27 mm pitch dual beam contacts
- Compatible with mPOWER® for power/signal flexibility
- Press-in or threaded standoffs available to assist with unmating (JSO)

ALSO AVAILABLE: HIGH-DENSITY SOLUTIONS

COMPRESSION INTERPOSERS
Low profile 1.27 mm body height and performance to 56 Gbps PAM4 (GMI)

PRECISION RF BOARD-TO-BOARD SOLUTIONS
SMP, SMPM and Ganged SMPM with a push-on design for quick installation and frequency to 65 GHz (GPPC, GPPB, SMPM, PRFIA, SMP).

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